ABSTRACT OF THE DISCLOSURE

INTEGRATED CIRCUIT ASSEMBLY CLEANING APPARATUS AND METHOD

An integrated circuit assembly cleaning apparatus and method allow a cleaning solution to completely fill spaces within the integrated circuit assembly. Such spaces include, for example, the thin space between the die and substrate of a flip-chip integrated circuit (100). The cleaning solution fills the space while the air initially occupying the space escapes. These actions are accomplished by first tilting the integrated circuit assembly from horizontal. The integrated circuit assembly is then immersed in the bath at a controllable rate to allow the cleaning solution to completely fill the space while the air in the space escapes.

Figure 5